

Amendments to the Claims

This listing of claims replaces all previous versions and listings of claims in this application.

1. (currently amended) A low-pressure discharge lamp comprising a tubular glass lamp vessel on an outer surface of which a conductor layer is formed as an electrode, wherein the conductor layer is ~~a solder dipping layer~~ formed by solder dipping and ~~the solder dipping layer~~ has a main component of any one of tin, an alloy of tin and indium, or an alloy of tin and bismuth.
2. (currently amended) A low-pressure discharge lamp according to claim 1, wherein the conductor ~~solder dipping~~ layer contains at least one of antimony, zinc, or aluminum as an additive.
3. (currently amended) A low-pressure discharge lamp according to claim 2, wherein a part of a surface of the tubular glass lamp vessel, where the conductor ~~solder dipping~~ layer is formed, is blasted.
4. (currently amended) A low-pressure discharge lamp comprising a tubular glass lamp vessel on an outer surface of which a conductor layer is formed as an electrode, wherein the conductor layer is ~~an ultrasonic solder dipping layer~~ formed by ultrasonic solder dipping.
5. (currently amended) A low-pressure discharge lamp according to claim 4, wherein the conductor ~~ultrasonic solder dipping~~ layer has a main component of any one of tin, an alloy of tin and indium, or an alloy of tin and bismuth.
6. (currently amended) A low-pressure discharge lamp according to claim 5, wherein the conductor ~~ultrasonic solder dipping~~ layer contains at least one of antimony, zinc, or aluminum as an additive.
7. (currently amended) A low-pressure discharge lamp according to claim 6, wherein a part of a surface of the tubular glass lamp vessel where the conductor ~~ultrasonic solder dipping~~ layer is formed is blasted.

8. (currently amended) A low-pressure discharge lamp according to claim 7, wherein the conductor ~~ultrasonic solder dipping~~ layer contains no lead component.

9-20. (cancelled)